



Device Material Content

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Package: 64 QFNS with matte Sn Plating
Total Device Weight 0.24 Grams

MSL: 3
Peak Reflow Temp: 260°C

July, 2009	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
Die	2.18%	0.005			Silicon chip	7440-21-3	Die size: 3.0 x 3.0 mm
Mold	51.46%	0.124	45.29%	0.109	Silica (fused)	60676-86-0	Mold Compound Density ranges between 1.9 and 2.1 grams/cc 75 to 95% Fused silica filler (LSC uses 88% in our calculation) 2 to 10% Epoxy resin (LSC uses 5% in our calculation) 2 to 10% Phenol resin (LSC uses 5% in our calculation) 0.5 to 2.5% Metal hydroxide (LSC uses 1.75% in our calculation) 0.1 to 0.5% Carbon Black (LSC uses 0.25% in our calculation)
			2.57%	0.0062	Epoxy Resin	-	
			2.57%	0.0062	Phenol Resin	-	
			0.90%	0.0022	Metal Hydroxide	-	
			0.13%	0.0003	Carbon Black	1333-86-4	
D/A Epoxy	0.38%	0.0009	0.29%	0.0007	Silver (Ag)	7440-22-4	Die attach epoxy Density: 4 grams/cc 70 to 80% Silver (LSC uses 75% in our calculation) 20 to 30% Organic Resins, Hardners and Elastomers (LSC uses 25% in our calculation)
			0.10%	0.0002	Organic esters and resins	-	
Wire	0.60%	0.0014			Gold (Au)	7440-57-5	Assume 1 wire per lead
Plating	0.28%	0.0007			Tin (Sn)	7440-31-5	Tin plating is 400 to 800 microinches (LSC uses 600 microinches in our calculation)
Leadframe	45.09%	0.108			Copper (Cu)	7440-50-8	

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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Rev. A